PRODUCT ADVISORY

Corrections to Standard Microcircuit Drawing 5962-00523 for Intersil Product IS-1009RH

Refer to:
PA11085

Date: August 26, 2011

intersil

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To: Our Valued Intersil Customers

Subject: **Corrections to Standard Microcircuit Drawing 5962-00523 for Intersil Product IS-1009RH**

This advisory is to inform you that Intersil has made corrections to DLA (Defense Logistics Agency) Land and Maritime SMD (Standard Microcircuit Drawing) 5962-00523 for the Intersil IS-1009RH products. The updates correct errors in the die thickness and glassivation as specified under Figure A-1 of Appendix A. There have been no changes to the die/silicon or product itself. The updated SMD is available on the DLA website at **http://www.dscc.dla.mil/downloads/milspec/smd/00523.pdf**.

Products Affected**:**

Intersil Part Number		**DLA SMD Part Number**
IS0-1009RH-Q	IS2-1009RH-QS9000	5962F0052301QXC
IS2-1009RH-8	IS2-1009RH-QS9002	5962F0052301QYC
IS2-1009RH-8S2731	ISYE-1009RH-8	5962F0052301V9A
IS2-1009RH-8S2732	ISYE-1009RH-Q	5962F0052301VXC
IS2-1009RH-8S9000	ISYE-1009RH-QS2732	5962F0052301VYA
IS2-1009RH-Q	ISYE-1009RH-QS9000	5962F0052301VYC
IS2-1009RH-QS2730	ISYE-1009RH-QS9003	
IS2-1009RH-QS2732	ISYES-1009RH-Q	

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to continue receiving product processed to the same established conditions and systems used for manufacturing of material supplied today.

If you have concerns with this advisory, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster

Jon Brewster
Intersil Corporation

PA11085

CC: J. Touvell J. Gill

PA11085 – Figure A-1 Updates

From:

Die physical dimensions.
  Die size: 50 mils x 70 mils
  Die thickness: 19 mils ± 1 mils

Interface materials.
  Top metallization: Al Si Cu 16.0 kÅ ± 2 kÅ
  Backside metallization: None (Silicon)

Glassivation.
  Type: Nitride (Si_3N_4) over silox (SiO_2)
  Nitride thickness: 4 kÅ ± 1 kÅ
  Silox thickness: 12 kÅ ± 4 kÅ

Substrate: DI (dielectric isolation)

Assembly related information.
  Substrate potential: Unbiased
  Special assembly instructions: None

To:

Die physical dimensions.
  Die size: 50 mils x 70 mils
  Die thickness: 14 mils ± 1 mils

Interface materials.
  Top metallization: Al Si Cu 16.0 kÅ ± 2 kÅ
  Backside metallization: None (Silicon)

Glassivation.
  Type: Nitride (Si_3N_4)
  Nitride thickness: 4 kÅ ± 1 kÅ

Substrate: DI (dielectric isolation)

Assembly related information.
  Substrate potential: Unbiased
  Special assembly instructions: None